# **HA22039**

# GaAs IC Low Distortion Mixer for Micro Wave Application

# **HITACHI**

ADE-207-271 (Z) Preliminary 1st. Edition August 1999

#### **Features**

- Suitable for low distortion of Micro Wave Application
- Low voltage and low current operation (3V, 7mA typ.)
- Low insertion loss (1.0 dB typ. @800MHz)
- Small surface mount package (MPAK–6)

#### Outline

MPAK-6



This Device si sensitive to Electro Static Discharge.

An Adequate handling procedure is requested.

#### CAUTION

This product ues GaAs. Since dust or fume of GaAs is highly poisonous to human body, please do not treat them mechanically in the manner which might expose to the Aer. And it should never be thrown out with general industrial or domestic wastes.

#### **Absolute Maximum Ratings (Ta = 25^{\circ}C)**

Item	Symbol	Ratings	Unit	
Supply voltage	Vdd	5	V	
Maximum current	ldd	60	mA	
Power dissipation	Pd	100	mW	
Channel temperature	Tch	150	°C	
Storage temperature	Tstg	-55 to +125	°C	
Operation temperature	Topr	-30 to +85	°C	

### HA22039

## Electrical Characteristics ( $Ta = 25^{\circ}C$ , Vdd = 3V, Idd = 7mA)

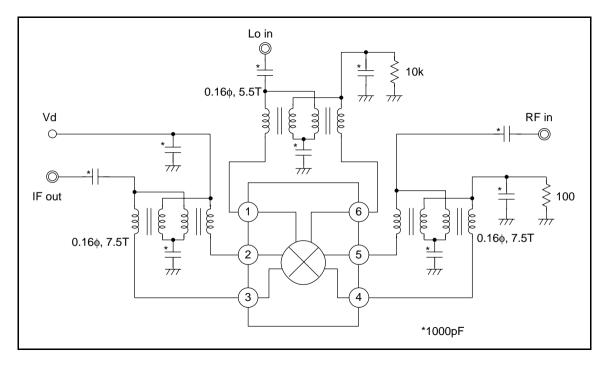
Item	Symbol	Min	Тур	Max	Unit	Test Conditions
Insertion loss	CL	0	1	3	dB	f = 800 MHz, PRF = -10dBm, Plo = 0dBm

### Typical Performance ( $Ta = 25^{\circ}C$ , Vdd = 3V, Idd = 7mA)

Item	Symbol	Тур	Unit	Test Conditions
3rd order input intercept point	IP3in	12	dBm	f = 800 MHz, PRF = -10dBm, Plo = 0dBm
Noise Figure (DSB)	NF	7	dB	

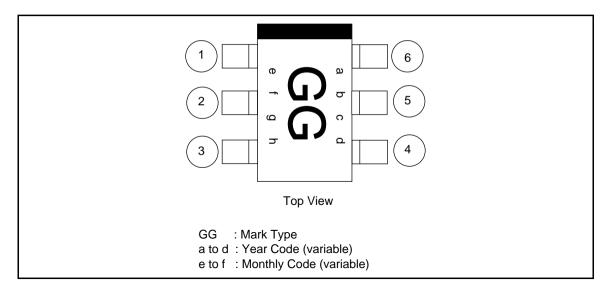
### **Block Diagram**

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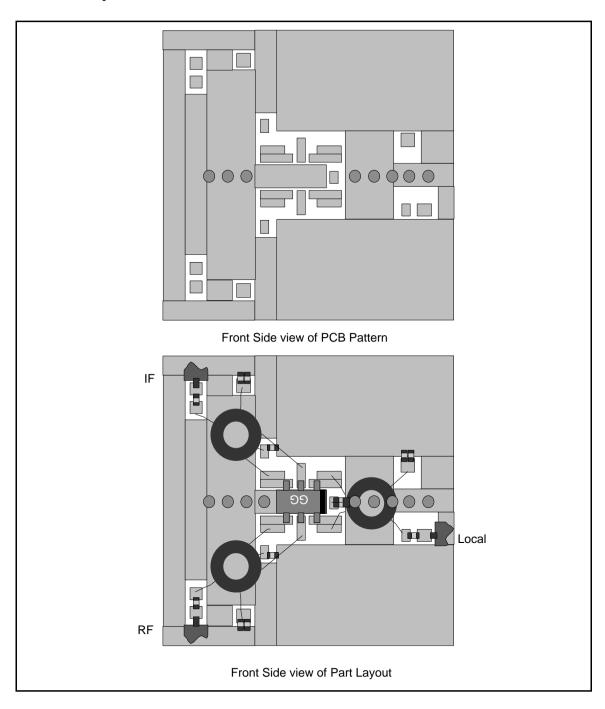
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### **Pin Arrangement**



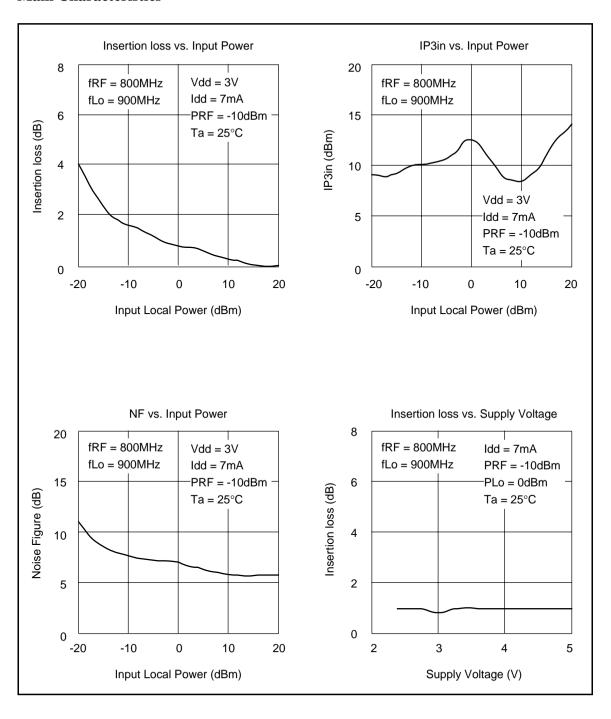
Pin No.	Pin name	Function
1	G1	Gate
2	D1	Drain
3	D2	Drain
4	S2	Source
5	S1	Source
6	G2	Gate

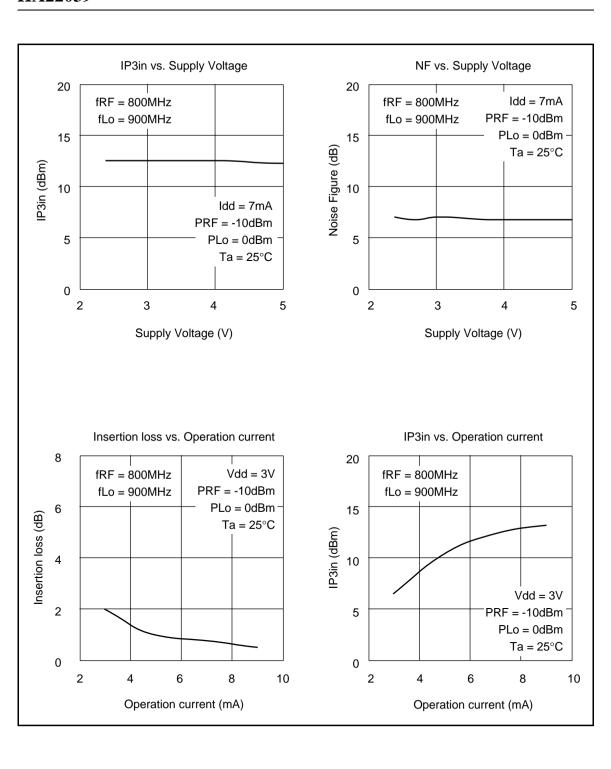
### **Pattern Layout**

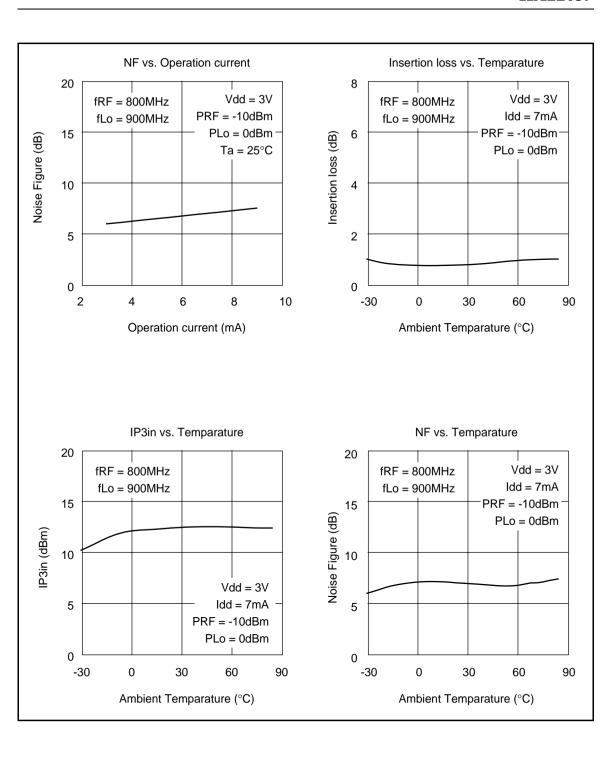


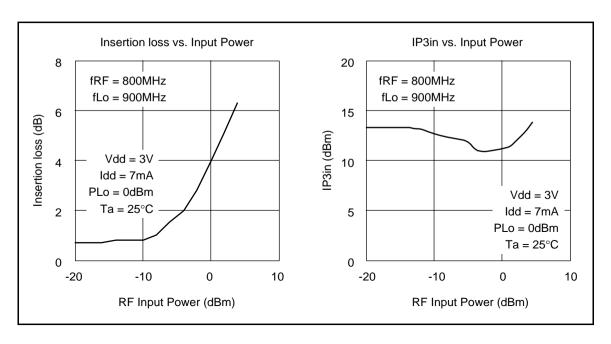
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#### **Main Characteristics**



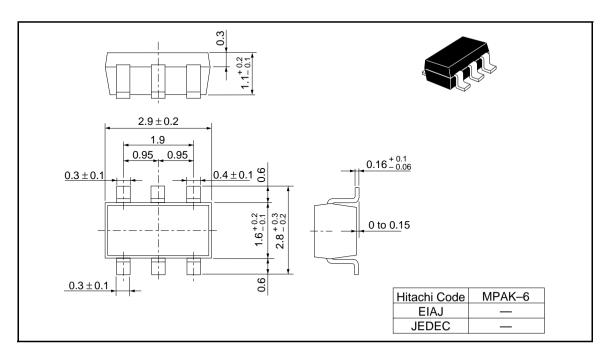






### **Package Dimentions**

Unit: mm



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